



Statement of Materials, Construction

40L PDIP TABLE OF MATERIAL DECLARATION								
No.	Name of the part	Material Name	Component Weight(mg) 1.00	Materials Analysis (Element)	CAS Number	Material Mass (milligram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy A194 w/Ag spot plating	1995.45	Cu	7440-50-8	1935.59 min	30.31 min	97 min
				Fe	7439-89-6	41.90-51.88	0.66-0.81	2.1-2.6
				Zn	7440-66-6	1.00-3.99	0.02-0.06	0.05-0.20
				Ag	7440-22-4	0.40-0.80	0.01	0.02-0.04
				P	7723-14-0	0.30-2.99	0.00-0.05	0.015-0.150
				Others	-	0.20 max	0.00	0.01 max
2	Die	Silicon Chip	5.50	Si	-	5.47	0.09	99.50
3	Die attach material	Conductive Epoxy Ablestik 2200D	1.18	Silver	7440-22-4	0.83-1.06	0.01-0.02	70-90
				Functionalized Urethane	-	0.06-0.18	0.00	5-15
				Diester resin	-	0.06-0.24	0.00	5-20
				Epoxy Resin	-	0.01-0.12	0.00	1-10
4	Wire	Gold	0.83	Au	7440-57-5	0.83	0.01	99.99
5	Lead Finish	Pure Tin	15.12	Sn	7440-31-5	15.10	0.24	99.9
6	Encapsulation	Epoxy Resin (EME G600V)	4367.36	Silica Fused	60676-86-0	3272.52-4148.99	51.30-64.98	75-95
				Epoxy Resin	-	87.35-349.39	1.37-5.47	2-8
				Epoxy, Cresol Novalac	29690-82-2	43.67-131.02	0.68-2.05	1-3
				Phenol Resin	-	87.35-349.39	1.37-5.47	2-8
				Carbon Black	1333-86-4	4.37-21.84	0.07-0.34	0.1-0.5
Total Package weight			6385.44					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%